

THE WORLD COMES HERE  
**TMS2019**  
148<sup>th</sup> Annual Meeting & Exhibition

# CALL FOR ABSTRACTS

March 10–14, 2019  
San Antonio, Texas, USA

## SUBMIT AN ABSTRACT TO:

### MATERIALS PROCESSING

#### Materials Processing Fundamentals

The key interest areas to be covered in this symposium are all aspects of the fundamentals, synthesis, analysis, design, monitoring, and control of metals, materials, and metallurgical processes and phenomena. Topics will include:

- The experimental, analytical, physical and computer modeling of physical chemistry and thermodynamics;
- Modeling on the transport phenomena in materials processing and metallurgical processes involving iron, steel, non-ferrous metals, and composites;
- Second phase particles in metals and processes, such as non-metallic inclusions and bubbles in metals (steel, aluminum, silicon, magnesium etc...) or gas bubbles in slag or electrolyte (foaming, gas evolution or injection...); the fundamentals (experimental studies or theoretical studies) on the nucleation, growth, motion and removal of these second phase particles from the molten metal or reactors;
- Physical chemistry, thermodynamics and kinetics for the production and refining of rare earth metals;
- Control of industrial processes in the field of extraction and processing of metals and materials: novel sensors for hostile-environment materials processes, such as online inclusion detection, temperature, and velocity in molten materials, surface condition of hot moving products, etc.; innovative online sampling and analysis techniques; models for real-time process control and quality monitoring systems.

### ORGANIZERS

**Guillaume Lambotte**, Boston Electrometallurgical Corporation, USA

**Jonghyun Lee**, Iowa State University, USA

**Antoine Allanore**, Massachusetts Institute of Technology, USA

**Samuel Robert Wagstaff**, Novelis, USA

Abstract Deadline is July 1, 2018.  
Submit online at [www.programmaster.org/TMS2019](http://www.programmaster.org/TMS2019)

Questions?  
Contact [programming@tms.org](mailto:programming@tms.org)